



**BSS138** 

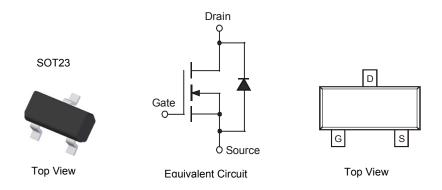
#### N-CHANNEL ENHANCEMENT MODE MOSFET

#### **Features**

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

### **Mechanical Data**

- Case: SOT23
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Terminal Connections: See Diagram
- Weight: 0.008 grams (approximate)



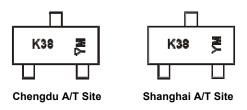
### **Ordering Information** (Note 4)

Part Number	Number Qualification Case		Packaging		
BSS138-7-F	Commercial	SOT23	3000/Tape & Reel		
BSS138Q-7-F	Automotive	SOT23	3000/Tape & Reel		

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant
- See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html

## **Marking Information**



K38 = Product Type Marking Code YM = Date Code Marking for SAT (Shanghai Assembly/ Test site)  $\overline{Y}$ M = Date Code Marking for CAT (Chengdu Assembly/ Test site) Y or  $\overline{Y}$  = Year (ex: A = 2013) M = Month (ex: 9 = September)

Date Code Key

Year	1998	1999	2000	2001	2002	2003	2004		2011	2012	2013	2014	2015	2016	2017
Code	J	K	L	М	N	Р	R		Υ	Z	Α	В	С	D	Е
Month	Jan	Fe	b I	Mar	Apr	May	Ju	n	Jul	Aug	Sep	Oc	t I	Nov	Dec
Code	1	2		3	4	5	6		7	8	9	0		N	D



# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Drain-Source Voltage	V <sub>DSS</sub>	50	V
Drain-Gate Voltage $R_{GS} \le 20 K\Omega$	$V_{DGR}$	50	V
Gate-Source Voltage Continuous	V	±20	V
Gate-Source Voltage Non repetitive, Pulse width<50µs	V <sub>GSS</sub>	±40	V
Drain Current Continuous	I <sub>D</sub>	200	mA
Pulsed Drain Current (10µs pulse duty cycle = 1%)	I <sub>DM</sub>	1	A

# Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

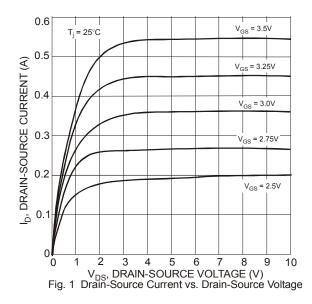
Characteristic	Symbol	Value	Units
Power Dissipation (Note 5)	$P_{D}$	300	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{ heta JA}$	417	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

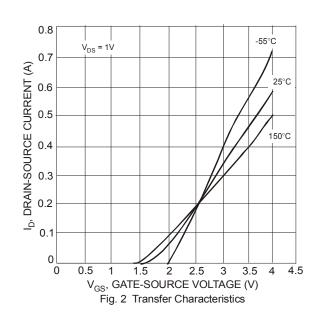
## **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition		
OFF CHARACTERISTICS (Note 6)								
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	50	75	_	V	$V_{GS} = 0V$ , $I_D = 250 \mu A$		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>			0.5	μΑ	$V_{DS} = 50V$ , $V_{GS} = 0V$		
Gate-Body Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$		
ON CHARACTERISTICS (Note 6)								
Gate Threshold Voltage	$V_{GS(th)}$	0.5	1.2	1.5	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$		
Static Drain-Source On-Resistance	R <sub>DS</sub> (ON)		1.4	3.5	Ω	$V_{GS} = 10V, I_D = 0.22A$		
Forward Transconductance	<b>9</b> FS	100		_	mS	$V_{DS} = 25V$ , $I_D = 0.2A$ , $f = 1.0KHz$		
DYNAMIC CHARACTERISTICS								
Input Capacitance	C <sub>iss</sub>			50	pF			
Output Capacitance	Coss			25	рF	$V_{DS} = 10V, V_{GS} = 0V, f = 1.0MHz$		
Reverse Transfer Capacitance	Crss		_	8.0	pF			
SWITCHING CHARACTERISTICS								
Turn-On Delay Time	$t_{D(ON)}$			20	ns	V = 20V I- = 0.24 D = 500		
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	_	20	ns	$V_{DD} = 30V$ , $I_D = 0.2A$ , $R_{GEN} = 50\Omega$		

Notes:

<sup>6.</sup> Short duration pulse test used to minimize self-heating effect.





<sup>5.</sup> Device mounted on FR-5 PCB 1.0 x 0.75 x 0.062 inch pad layout as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at http://www.diodes.com.



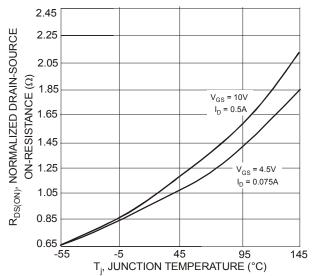


Fig. 3 Drain-Source On-Resistance vs. Junction Temperature

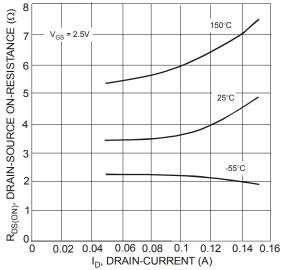


Fig. 5 Drain-Source On-Resistance vs. Drain-Current

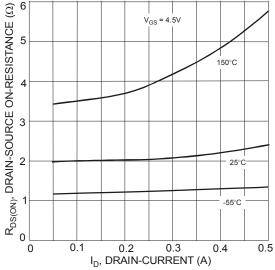


Fig. 7 Drain-Source On-Resistance vs. Drain-Current

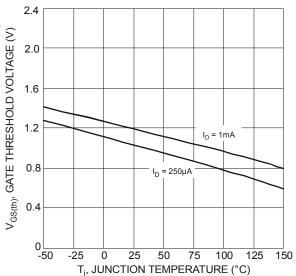


Fig. 4 Gate Threshold Variation vs. Ambient Temperature

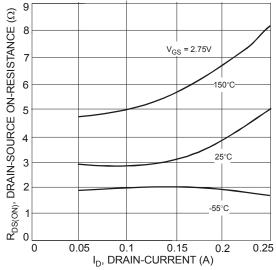


Fig. 6 Drain-Source On-Resistance vs. Drain-Current

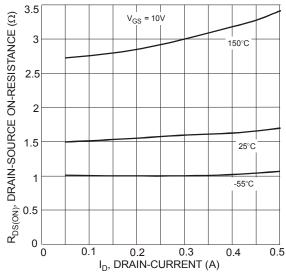
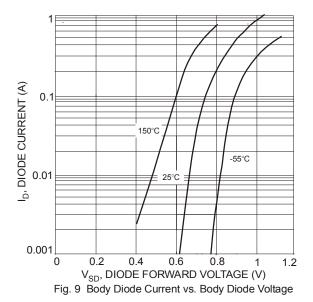
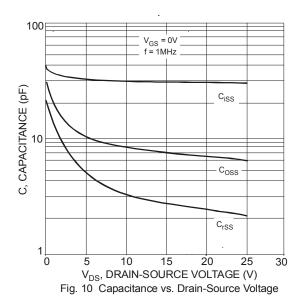


Fig. 8 Drain-Source On Resistance vs. Drain-Current

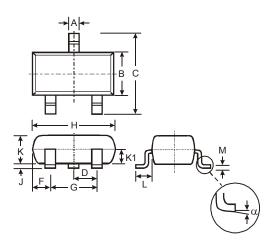






## **Package Outline Dimensions**

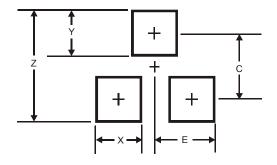
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT23								
Dim	Min	Max	Тур					
Α	0.37	0.51	0.40					
В	1.20	1.40	1.30					
C	2.30	2.50	2.40					
D	0.89	1.03	0.915					
F	0.45	0.60	0.535					
G	1.78	2.05	1.83					
Н	2.80	3.00	2.90					
7	0.013	0.10	0.05					
K	0.903	1.10	1.00					
K1	-	-	0.400					
١	0.45	0.61	0.55					
М	0.085	0.18	0.11					
α	0°	8°	-					
All Dimensions in mm								

## Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)			
Z	2.9			
Х	0.8			
Υ	0.9			
С	2.0			
E	1.35			



#### IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

#### **LIFE SUPPORT**

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
  - 1. are intended to implant into the body, or
  - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2013, Diodes Incorporated

www.diodes.com